



# SLOVENSKI STANDARD

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SIST EN 16602-70-08:2015

SIST EN 16602-70-38:2019

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**Zagotavljanje vesoljskih izdelkov - visoko zanesljivo spajkanje za površinski nosilec, mešano tehnologijo in ročno vgrajene električne priključke**

Space product assurance - High-reliability soldering for surface mount, mixed technology and hand-mounted electrical connections

Raumfahrtproduktsicherung - Hochzuverlässiges Löten von Oberflächen-Befestigungen und Durchgangslochverbindungen

Assurance produit spatiale - Assamblage haute fiabilité pour technologies à montage de surface et connexions traversantes

**Ta slovenski standard je istoveten z: prEN 16602-70-61**

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**ICS:**

25.160.50	Trdo in mehko lotanje	Brazing and soldering
49.140	Vesoljski sistemi in operacije	Space systems and operations

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**en**

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## Space product assurance - High-reliability soldering for surface mount, mixed technology and hand-mounted electrical connections

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Raumfahrtproduktsicherung - Hochzuverlässiges Löten von Oberflächen-Befestigungen und Durchgangslochverbindungen

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## European Foreword

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